

090454-010808

These materials demonstrate that, at the time of the application for U.S. Patent 5,483,421, Mr. Gedney and others skilled in electronic packaging materials knew that the coefficient of thermal expansion for glass-filled epoxy dielectric materials suitable for electronic packaging could be  $15 \times 10^{-6}$  ppm/°C or less. Thus, these values for coefficients of thermal expansion are inherent in the disclosure of glass filled epoxy dielectric material and the addition of these values in this application should not be considered new matter.

By: [Signature]

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